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UTILITY PATENT APPLICATION TRANSMITTAL

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Attorney Docket No. **0756-2203**

First Inventor or Application Identifier **Shunpei YAMAZAKI**

Title: **ELECTRO-OPTICAL DEVICE AND METHOD FOR
MANUFACTURING THE SAME**

Express Mail Label No.

APPLICATION ELEMENTS

See MPEP chapter 600 concerning utility patent application contents.

ADDRESS TO:

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1. ☒ Fee Transmittal Form (e.g., PTO/SB/17)
(Submit an original, and a duplicate for fee processing)
2. ☒ Specification Total Pages [29]
(preferred arrangement set forth below)
- Descriptive title of the Invention
 - Cross References to Related Applications
 - Statement Regarding Fed sponsored R & D
 - Reference to Microfiche Appendix
 - Background of the Invention
 - Brief Summary of the Invention
 - Brief Description of the Drawings (if filed)
 - Detailed Description
 - Claim(s)
 - Abstract of the Disclosure
3. ☒ Drawing(s) (35 USC 113) Total Sheets [10]
4. ☒ Oath or Declaration Total Pages []
- a. ☐ Newly executed (original or copy)
 - b. ☒ Copy from a prior application (37 CFR 1.63(d))
(for continuation/divisional with Box 17 completed)
[Note Box 5 below]
 - i. ☐ **DELETION OF INVENTOR(S)**
Signed statement attached deleting
inventor(s) named in the prior application,
see 37 CFR 1.63(d)(2) and 1.33(b).
5. ☐ Incorporation By Reference (useable if Box 4b is checked)
The entire disclosure of the prior application, from which a
copy of the oath or declaration is supplied under Box 4b,
is considered to be part of the disclosure of the
accompanying application and is hereby incorporated by
reference therein.

6. ☐ Microfiche Computer Program (Appendix)
7. Nucleotide and/or Amino Acid Sequence Submission
(if applicable, all necessary)
- a. ☐ Computer Readable Copy
 - b. ☐ Paper Copy (identical to computer copy)
 - c. ☐ Statement verifying identity of above copies

ACCOMPANYING APPLICATION PARTS

8. ☐ Assignment Papers (cover sheet & document(s))
9. ☐ 37 CFR 3.73(b) Statement [] Power of Attorney
(when there is an assignee)
10. ☐ English Translation Document (if applicable)
11. ☒ Information Disclosure Statement [X] Copies of IDS
(IDS)/PTO-1449 Citations
12. ☒ Preliminary Amendment
13. ☒ Return Receipt Postcard (MPEP 503)
(Should be specifically itemized)
14. ☐ *Small Entity [] Statement filed in prior application,
Statement(s) Status still proper and desired
(PTO/SB/09-12)
15. ☐ Certified Copy of Priority Document(s)
(if foreign priority is claimed)
16. ☐ Other:

*A new statement is required to be entitled to pay small entity fees,
except where one has been filed in a prior application and is being
relied upon.

17. If a **CONTINUING APPLICATION**, check appropriate box, and supply the requisite information below and in a preliminary amendment

☒ Continuation ☐ Divisional ☐ Continuation-in-part (CIP) of prior application No. 08/962,601
Prior application information: Examiner: J. Jackson, Jr. Group/Art Unit: 2815

18. CORRESPONDENCE ADDRESS

☒ Customer Number or Bar Code Label

Customer No. 22204

or ☐ Correspondence address below

(Insert Customer No. or Attach bar code label here)

Name Eric J. Robinson
Firm NIXON PEABODY LLP
Address 8180 Greensboro Drive, Suite 800
City McLean State VA
Country U S A Telephone (703) 790-9110

Zip Code 22102
FAX (703) 883-0370

Name: Eric J. Robinson

Registration No. 38,285

Signature

Date. September 5, 2000

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2/A

In re Application of)	Group Art Unit: 1109
)	
SHUNPEI YAMAZAKI)	Examiner: R. Kunemund
)	
Serial No.: (NOT YET ASSIGNED))	
)	
Filed: September 5, 2000)	
)	
For: ELECTO-OPTICAL DEVICE AND)	
METHOD FOR MANUFACTURING)	
THE SAME)	Date: September 5, 2000

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D. C. 20231

Sir:

Before examination on the merits, please amend the application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Page 1, between lines 3 and 4, please insert the following:

--This application is a Continuation of application No. 08/962,602, filed October 31, 1997 (now U.S. Patent 6,023,075), which is a Division of application No. 08/231,644, filed April 22, 1994 (now U.S. Patent 5,849,601); which itself is a division of Serial No.

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08/217,211, filed March 24, 1994, now abandoned; which is a continuation of Serial No. 07/811,063, filed December 20, 1991, now abandoned, and this application is a continuation-in-part of Serial No. 08/293,201 filed August 19, 1994 (now U.S. Patent 5,614,732); which was a continuation of Serial No. 07/967,564, filed October 28, 1992, now abandoned; which was a continuation of Serial No. 07/673,821, filed March 22, 1991, now abandoned.--

IN THE CLAIMS:

Please cancel claims 1-20.

Please add the following new claims:

--21. An active matrix display device having a pixel portion and a peripheral circuit portion, said peripheral portion including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and a part of the peripheral circuit portion,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^5 to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

22. A semiconductor circuit having a pixel portion and a shift register, said shift register including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor. each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and the shift register,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}.\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}.\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

23. A semiconductor circuit having a pixel portion and an inverter said inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and
a gate electrode adjacent to said gate insulating film;
a leveling film covering each of said thin film transistors in both of the pixel portion and the inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less.

24. A semiconductor circuit having a pixel portion and a clocked inverter said clocked inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and the clocked inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^5 to 1×10^{18} ,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

25. An active matrix display device having a pixel portion and a peripheral circuit portion, said peripheral portion including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and a part of the peripheral circuit portion,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of 10 cm²/V.sec or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of 15 cm²/V.sec or more, and

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to 1×10^{18} cm⁻³ to control an absolute value of a threshold voltage of said n-channel thin film transistor to be substantially the same as an absolute value of a threshold voltage of said p-channel thin film transistor,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

26. A semiconductor circuit having a pixel portion and a shift register said shift register including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor

island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and in the shift register,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more, and

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$ to control an absolute value of a threshold voltage of said n-channel thin film transistor to be substantially the same as an absolute value of a threshold voltage of said p-channel thin film transistor,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less.

27. A semiconductor circuit having a pixel portion and an inverter said inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said thin film transistors in both of the pixel portion and the inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more, and

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$ to control an absolute value of a threshold voltage of said n-channel thin film transistor to be substantially same the as an absolute value of a threshold voltage of said p-channel thin film transistor,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

28. A semiconductor circuit having a pixel portion and a clocked inverter said clocked inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film,

a leveling film covering each of said thin film transistors in both of the pixel portion and the clocked inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V} \cdot \text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V} \cdot \text{sec}$ or more, and

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$ to control an absolute value of a threshold voltage of said n-channel thin film transistor to be substantially the same as an absolute value of a threshold voltage of said p-channel thin film transistor,

wherein each of said semiconductor islands has a thickness in the range of 5000 Å or less.

29. An active matrix display device having a pixel portion and a peripheral circuit

portion, said peripheral portion including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film;

a leveling film covering each of said p-channel and n-channel thin film transistors in both of the pixel portion and a part of the peripheral circuit portion,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}\cdot\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less,

wherein each of said semiconductor islands comprises oxygen at a concentration not higher than $7 \times 10^{19} \text{ cm}^{-3}$.

30. A semiconductor circuit having a pixel portion and a shift register said shift register including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film,

a leveling film covering each of said thin film transistors in both of the pixel

portion and the shift register,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}.\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}.\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less,

wherein each of said semiconductor islands comprises oxygen at a concentration not higher than $7 \times 10^{19} \text{ cm}^{-3}$.

31. A semiconductor circuit having a pixel portion and an inverter said inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film,

a leveling film covering each of said thin film transistors in both of the pixel portion and the inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V}.\text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V}.\text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less,

wherein each of said semiconductor islands comprises oxygen at a concentration not higher than $7 \times 10^{19} \text{ cm}^{-3}$.

32. A semiconductor circuit having a pixel portion and a clocked inverter said clocked inverter including at least one pair of complementary p-channel and n-channel thin film transistors, and said pixel portion including at least one thin film transistor, each of said transistors comprising:

a crystalline semiconductor island on an insulating surface, said semiconductor island having source and drain regions and a channel region;

a gate insulating film adjacent to at least said channel region; and

a gate electrode adjacent to said gate insulating film,

a leveling film covering each of said thin film transistors in both of the pixel portion and the clocked inverter,

wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of $10 \text{ cm}^2/\text{V} \cdot \text{sec}$ or more and said semiconductor island of n-channel thin film transistor has an electron mobility in the range of $15 \text{ cm}^2/\text{V} \cdot \text{sec}$ or more,

wherein at least one of said semiconductor islands comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said semiconductor islands has a thickness in the range of 5000 \AA or less,

wherein each of said semiconductor islands comprises oxygen at a concentration not higher than $7 \times 10^{19} \text{ cm}^{-3}$.

33. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said semiconductor is silicon.

34. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said gate electrode comprises crystalline silicon doped with phosphorus.

35. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said gate electrode is a multilayer film of crystalline silicon doped with phosphorus and a metal film thereon, said metal comprising at least a material selected from the group consisting of Mo, W, MoSi₂, and WSi₂.

36. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said semiconductor island comprises oxygen at a concentration not higher than $1 \times 10^{19} \text{ cm}^{-3}$.

37. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said crystalline semiconductor island exhibits a Raman peak shifted to a lower frequency side from 522 cm^{-1} .

38. A circuit according to claim 34 wherein said phosphorus doped in said crystalline silicon is at a concentration of 1×10^{21} to $5 \times 10^{21} \text{ cm}^{-3}$.

39. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said source and drain regions of n-channel thin film transistor are introduced with phosphorus at a dose of 1×10^{15} to $5 \times 10^{15} \text{ cm}^{-3}$.

40. A circuit according to any one of claims 22-24, 26-28, and 30-32 wherein said semiconductor island has a thickness of 500-5000 Å.

41. An active matrix display device including a pixel portion and a peripheral circuit portion comprising:

a plurality of pixel electrodes formed on an insulating surface;

a first plurality of thin film transistors being formed in the pixel portion on said insulating surface and being connected to said pixel electrodes;

a second plurality of thin film transistors being formed in the peripheral circuit portion on said insulating surface, said second plurality of thin film transistors including at least one pair of complementary p-channel and n-channel thin film transistors;

a leveling film covering both of the first and second plurality of thin film transistors in the pixel portion and a part of the peripheral circuit portion,

wherein said second plurality of thin film transistors in said peripheral circuit include channel semiconductor layers having at least one of an electron mobility $15 \text{ cm}^2/\text{V.s}$ or more and a hole mobility of $10 \text{ cm}^2/\text{V.s}$ or more,

wherein each of the channel semiconductor layers comprises boron at a concentration in the range of 1×10^{15} to $1 \times 10^{18} \text{ cm}^{-3}$,

wherein each of said channel semiconductor layers has a thickness of 5000 \AA or less.

42. An active matrix display device including a pixel portion and a peripheral circuit portion comprising:

a plurality of pixel electrodes formed on an insulating surface;

a first plurality of thin film transistors being formed in the pixel portion on said insulating surface and being connected to said pixel electrodes;

a second plurality of thin film transistors being formed in the peripheral portion on said insulating surface, said second plurality of thin film transistors including at least one pair of complementary p-channel and n-channel thin film transistors;

a leveling film covering both of the first and second plurality of thin film transistors in the pixel portion and a part of the peripheral circuit portion,

wherein said second thin film transistors in said peripheral circuit include channel semiconductor layers comprising silicon in which oxygen is contained at a concentration not higher than $7 \times 10^{19} \text{ cm}^{-3}$,

wherein each of said channel semiconductor layers has a thickness of 5000 \AA or less.

43. A device according to claim 41 or 42 wherein said semiconductor is silicon.

44. A device according to claim 41 or 42 wherein each of the first and second plurality of said thin film transistors comprises a gate electrode formed over said channel semiconductor layers having a gate insulating film therebetween.

45. A device according to claim 44 wherein said gate electrode comprises crystalline silicon doped with phosphorus.

46. A device according to claim 44 wherein said gate electrode is a multilayer film of crystalline silicon doped with phosphorus and a metal film thereon, said metal comprising at least a material selected from the group consisting of Mo, W, MoSi₂, and WSi₂.

47. A device according to claim 45 or 46 wherein said phosphorus doped in said crystalline silicon is at a concentration of 1×10^{21} to 5×10^{21} cm⁻³.

48. A device according to claim 41 or 42 wherein said channel semiconductor layers exhibit a Raman peak shifted to a lower frequency side from 522 cm⁻¹.

49. A device according to any one of claims 21, 25, and 29 wherein said semiconductor is silicon.

50. A device according to any one of claims 21, 25, and 29 wherein said gate electrode comprises crystalline silicon doped with phosphorus.

51. A device according to any one of claims 21, 25, and 29 wherein said gate electrode is a multilayer film of crystalline silicon doped with phosphorus and a metal film

thereon, said metal comprising at least a material selected from the group consisting of Mo, W, MoSi₂, and WSi₂.

52. A device according to any one of claims 21, 25, and 29 wherein said semiconductor island comprises oxygen at a concentration not higher than $1 \times 10^{19} \text{ cm}^{-3}$.

53. A device according to any one of claims 21, 25, and 29 wherein said crystalline semiconductor island exhibits a Raman peak shifted to a lower frequency side from 522 cm^{-1} .

54. A device according to claim 30 or 31 wherein said phosphorus doped in said crystalline silicon is at a concentration of 1×10^{21} to $5 \times 10^{21} \text{ cm}^{-3}$.

55. A device according to any one of claims 21, 25, and 29 wherein said source and drain regions of n-channel thin film transistor are introduced with phosphorus at a dose of 1×10^5 to $5 \times 10^5 \text{ cm}^{-3}$.

56. A device according to any one of claims 21, 25, and 29 wherein said semiconductor island has a thickness of 500-5000 Å.

57. A circuit according to any one of claims 22-24, 26-28, and 30-32, wherein said leveling film comprises an organic resin.

58. A circuit according to claim 57, wherein said organic resin is a transparent polyimide resin.

59. A device according to any one of claims 21, 25, 29, 41 and 42, wherein said leveling film comprises an organic resin.

60. A device according to claim 59, wherein said organic resin is a transparent polyimide resin.

61. A circuit according to any one of claims 22-24, 26-28, and 30-32, wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of 200 cm²/V.sec or less and said semiconductor island of n-channel thin film transistor has a electron mobility in the range of 300 cm²/V.sec or less.

62. A device according to any one of claims 21, 25, and 29, wherein said semiconductor island of p-channel thin film transistor has a hole mobility in the range of 200 cm²/V.sec or less and said semiconductor island of n-channel thin film transistor has a electron mobility in the range of 300 cm²/V.sec or less.

63. A device according to claim 41, wherein said second plurality of thin film transistors in said peripheral circuit include channel semiconductor layers having at least one of an electron mobility 300 cm²/V.s or less and a hole mobility of 200 cm²/V.s or less.

64. A circuit according to any one of the claims 22-24, and 30-32, wherein said n-channel thin film transistor has an approximately same absolute value of a threshold voltage as said p-channel thin film transistor.

65. A device according to any one of the claims 21, 25, 29, wherein said n-channel thin film transistor has an approximately same absolute value of a threshold voltage as said p-channel thin film transistor.

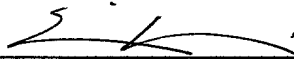
66. A circuit according to claim 35 wherein said phosphorus doped in said crystalline silicon is at a concentration of 1×10^{21} to 5×10^{21} cm⁻³.--

REMARKS

In view of the above, the present application is believed to be in condition for allowance, and a *Notice of Allowance* is earnestly solicited. If the Examiner has any further questions concerning this application, he is invited to contact the undersigned.

Respectfully submitted,

NIXON PEABODY LLP



Eric J. Robinson

Registration No. 38,285

8180 Greensboro Drive, Suite 800

McLean, Virginia 22102

Telephone (703) 790-9110

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TITLE OF THE INVENTION

ELECTRO-OPTICAL DEVICE AND METHOD FOR MANUFACTURING THE SAME

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to an electro-optical device which comprises thin film transistors (referred to hereinafter as TFTs) and to a method for manufacturing such a device.

2. Description of the Prior Art

More attention is now paid to flat displays than to CRTs (cathode ray tubes) for use in office automation (OA) machines and the like, and particularly, there is an increasing demand for large-area display devices. There is also an active and rapid development in the application field of flat displays such as wall television (TV) sets. Furthermore, there are demands for color flat displays and finer display images.

A liquid crystal display device is known as a representative example of a flat display. A liquid crystal display device comprises a pair of glass substrates having incorporated therebetween a liquid crystal composition together with electrodes, and the images are displayed by the change of state of the liquid crystal composition upon application of an electric field thereto. The liquid crystal cells may be driven by the use of a TFT or other switching devices, or by making it into a simple matrix structure. In any case, a driver circuit is established at the periphery of a display to supply signals for driving liquid crystals to column lines (extending in Y

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direction) and row lines (extending in X direction).

The driver circuit is generally composed of a single crystal silicon MOS integrated circuit (IC). The IC is provided with pad electrodes, each corresponding to each of the display electrodes, and a printed circuit board is incorporated between the pad and the display electrodes to connect first the pad electrode of the IC with the printed circuit board and then the printed circuit board with the display. The printed circuit board, which in general is made of an insulator board made from materials such as a glass fiber-reinforced epoxy resin or a paper filled epoxy resin, or of a flexible plastic board, requires an area equivalent to or even larger than the display area. Similarly, the volume thereof should have to be made considerably large.

Thus, because of the construction as described hereinabove, a conventional display suffers problems as follows:

(1) A superfine display cannot be realized. Since each of the wirings of the display electrodes for the X direction and the Y direction of the matrix, or the source (drain) wirings or the gate wirings should be connected individually to each of the contacts on the printed board, the minimum distance between the connecting portions technologically achievable by the up-to-date surface mounting technology is limited to a certain length;

(2) A display device as a whole occupies a large area and volume. A display device comprises indispensable parts in addition to the display itself, inclusive of the printed circuit board, the ICs, and the connecting wirings, which require an area and volume about several times as large as those of the display alone; and

(3) The connections are of low reliability. Quite a large number of connections should be established between the main display and the printed circuit board, as well as between the printed circuit board and the ICs; moreover, not a small weight

is casted on the connecting portions.

As a means to overcome the foregoing problems, there is proposed, particularly in a display device comprising an active matrix as the switching device, to construct a display device comprising the active device and the peripheral circuits on a same substrate using TFTs rather than semiconductor chips. Such a construction indeed solves the three problems mentioned hereinabove, however, it newly develops problems as follows:

(4) The production yield of the display is low. Since the peripheral circuits also are made from TFTs, the number of the devices to be fabricated on the same substrate is increased and hence the production yield of the TFT is lowered;

(5) The production cost is increased. Since the peripheral circuit portion comprises a very complicated device structure, the circuit pattern accordingly becomes complicated and hence the cost increases. Furthermore, with the increase in the multilayered wiring portion, an increase in process steps as well as a decrease in the production yield of the TFTs occur; and

(6) It requires a treatment at a high temperature and hence the use of an expensive quartz substrate becomes requisite. Since a quick response is required to the transistors which constitute the peripheral circuit, the semiconductor layer should be treated at a high temperature to obtain a polycrystalline layer to be used as the transistors.

SUMMARY OF THE INVENTION

An object of the present invention is to overcome the six problems mentioned above by taking balance among them and to provide a more economical electro-optical device at a high yield.

This and other objects of the present invention have been attained by an electro-optical device comprising a pair of

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substrates and an electro-optical modulating layer having sandwiched therebetween, said pair of substrates consisting of a first substrate having provided thereon thin film transistors and matrix lines comprising a plurality of gate wires (extending e.g. in Y direction) and a plurality of source (drain) wires (extending e.g. in X direction), and a second substrate facing the first substrate, wherein, among the peripheral circuits being connected to the matrix lines, only one direction side of said peripheral circuits is constructed from thin film semiconductor devices fabricated by the same process utilized for the thin film transistors, and the rest of the peripheral circuits is constructed from semiconductor chips. The electro-optical modulating layer may comprise a liquid crystal.

In the electro-optical device according to the present invention, the peripheral circuit only on one side is fabricated as TFTs. In such a manner, a general use economical ICs can be utilized on one side, while fabricating the side comprising peripheral circuits which are not commercially available or which are costly, as TFTs.

Furthermore, by making only one side into TFTs, the number of the TFTs in the peripheral circuit portion can be considerably reduced. For example, the number of the TFTs can be halved in case the peripheral circuits for the X and the Y directions have the same function. Thus, the production yield of a TFT on the same substrate is increased by two times in a simple calculation.

According to another embodiment of the present invention, there is provided an electro-optical device comprising a first substrate having provided thereon a pixel matrix furnished with complementary TFTs and matrix lines comprising a plurality of gate wires (extending e.g. in Y direction) and a plurality of source (drain) wires (extending e.g. in X direction), said first substrate making a pair with a second substrate faced thereto and

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an electro-optical modulating layer having supported between the pair of substrates, characterized by that at least a part of the peripheral circuits being connected to the matrix lines is fabricated into complementary TFTs similar in structure of the active matrix (e.g. the complementary TFTs of the pixel matrix) and being fabricated also in a same process as that of the active matrix, and that the rest of the peripheral circuits are constructed by semiconductor chips, said peripheral circuits being connected to the X or Y direction matrix wires having established on the first substrate. The electro-optical modulating layer may comprise a liquid crystal.

More precisely, the electro-optical device according to the present invention is characterized by that the peripheral circuit is not wholly fabricated into TFTs, but only those portions having a simple device structure, or those composed of a small number of devices, or those comprising an IC not easily available commercially, or those comprising an expensive IC, are fabricated as TFTs. It is therefore an object of the present invention to increase the production yield and to reduce the production cost of an electro-optical device.

Accordingly, by fabricating a part of the peripheral circuits as TFTs, the number of external ICs is reduced and therefore the production cost is reduced.

Furthermore, by fabricating the peripheral circuits and the active matrix in the same process to give complementary TFTs (CTFTs), the pixel driving capacity is increased and a redundancy is imparted to the peripheral circuit. Hence it is possible to drive the electro-optical device with a greater allowance.

If the peripheral circuits were to be wholly fabricated into TFTs, the device requires extension of the display substrate along both of the X and Y directions. This inevitably leads to an unfavorable increase in the total occupancy area. In contrast, if

surface mounting technology (SMT) such as a Chip on Glass (COG) process which comprises directly mounting the IC chips on a substrate and connecting them with each of the connecting terminals, and a Tape Automated Bonding (TAB) process which comprises mounting each of the IC chips on a flexible support made of an organic resin, and then connecting the resin support with the display substrate.

It is further possible to fabricate the semiconductor layers of the TFTs at a lower temperature and yet to realize quick response TFTs having a considerably increased carrier mobility by taking advantage of, instead of the conventional polycrystalline or amorphous semiconductors, a semi-amorphous semiconductor which is based on a novel concept.

The semi-amorphous semiconductor can be obtained by applying a heat treatment to crystallize a thin film having deposited by processes such as low-pressure chemical vapor deposition (LPCVD), sputtering, plasma-assisted chemical vapor deposition (PCVD), and the like. The process for fabricating a semi-amorphous semiconductor film is described below referring to the sputtering process as an example.

In depositing a film by sputtering from a single crystal target of a silicon semiconductor under a mixed gas atmosphere comprising hydrogen and argon, the heavy argon atoms strike the surface of the silicon target to release free silicon atoms. The free silicon atoms thus released from the target then travel to the substrate on which the film is to be deposited, accompanied by clusters composed of several tens to several millions of silicon atoms. During their travel in the sputtering chamber, hydrogen atoms come to bond with the dangling bonds of the silicon atoms located at the outer periphery of the clusters, and these clusters comprising the silicon-hydrogen bonding are maintained to the surface of the substrate to deposit as a

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relatively ordered region. Thus, a highly ordered film comprising a mixture of amorphous silicon and clusters accompanied by Si-H bondings on the periphery is realized on the surface of the substrate. By further heat treating the deposited film in the temperature range of from 450 to 700°C in a non-oxidizing atmosphere, the Si-H bondings on the outer periphery of the clusters react with each other to yield Si-Si bondings. The Si-Si bondings thus obtained exert a strong attractive force to each other. At the same time, however, the clusters in their highly ordered state are susceptible to undergo phase transition to attain a more ordered state, i.e., a crystallized state. Thus, because the Si-Si bondings in the neighboring clusters attract each other, the resulting crystals suffer lattice distortion which can be observed by laser Raman spectroscopy as a peak deviated in position to the lower frequency side from the 520 cm^{-1} which corresponds to the peak of a single crystal of silicon.

Furthermore, since the Si-Si bondings between the neighboring clusters cause anchoring (connecting) effects, the energy band in each cluster is electrically connected with that of the neighboring cluster through the anchored locations. Accordingly, since there is no grain boundaries as in the conventional polycrystalline silicon which function as a barrier to the carriers, a carrier mobility as high as in the range of from 10 to 200 $\text{cm}^2/\text{V}\cdot\text{sec}$ can be obtained. That is, the semi-amorphous semiconductor defined above is apparently crystalline, however, if viewed from the electrical properties, there can be assumed a state substantially free from grain boundaries. If the annealing of a silicon semiconductor were to be effected at a temperature as high as 1000°C or over, instead of a moderate annealing in the temperature range of from 450 to 700°C as referred hereinbefore, the crystallization naturally would induce

invention;

FIG. 8 is a schematic view illustrating a liquid crystal display device according to another embodiment of the present invention, composed of an $m \times n$ circuit structure; and

FIG. 9 is a schematic representation of a liquid crystal display device according to another embodiment of the present invention.

DETAILED DESCRIPTION OF THE PRESENT INVENTION

The present invention is described in further detail below referring to non-limiting examples.

EXAMPLE 1

Referring to FIG. 1, a liquid crystal display device having an $m \times n$ circuit structure is described. In FIG. 2 is also given the outer appearance of the liquid crystal display device. In FIG. 1, a shift resistor circuit portion 1 (a means for supplying a signal to a wiring of the X direction) being connected to a wiring of the X direction is solely fabricated as TFTs 5 in a similar manner as an active device provided to a pixel 6, and a peripheral circuit portion (a means for supplying a signal to a wiring of the Y direction) connected to a wiring of the Y direction is provided as ICs 4 which is connected to the substrate by TAB. The thin film transistors provided in the pixel 6 as the active device and the thin film transistors 5 constituting the shift resistor circuit portion 1 are provided on a single substrate.

The actual arrangement of the electrodes and the like corresponding to this circuit structure is shown in FIG. 6. In FIG. 6, however, the structure is simplified and shown in a 2×2

back pressure prior to sputtering was controlled to 1×10^{-5} Pa or lower. The film was deposited at a film deposition temperature of 150°C , a frequency of 13.56 MHz, a sputter output of from 400 to 800 W, and a pressure of 0.5 Pa.

In case of the deposition of a silicon film by a PCVD process, the temperature was maintained, e.g., at 300°C , and monosilane (SiH_4) or disilane (Si_2H_6) was used as the reacting gas. A high frequency electric power was applied at 13.56 MHz to the gas inside the PCVD apparatus to effect the film deposition.

The films thus obtained by any of the foregoing processes preferably contain oxygen at a concentration of $5 \times 10^{21} \text{ cm}^{-3}$ or lower. If the oxygen concentration is too high, the film thus obtained would not crystallize. Accordingly, there would be required to elevate the thermal annealing temperature or to take a longer time for the thermal annealing. Too low an oxygen concentration, on the other hand, increases an off-state leak current due to a backlighting. Accordingly, the preferred range of the oxygen concentration was set in the range of from 4×10^{19} to $4 \times 10^{21} \text{ atoms}\cdot\text{cm}^{-3}$. The hydrogen concentration was for example $4 \times 10^{22} \text{ atoms}\cdot\text{cm}^{-3}$, which accounts for 1 % by atomic with respect to the silicon concentration of $4 \times 10^{22} \text{ atoms}\cdot\text{cm}^{-3}$. To enhance crystallization of the source and drain portions, oxygen concentration is $7 \times 10^{19} \text{ atoms}\cdot\text{cm}^{-3}$ or less, preferably $1 \times 10^{19} \text{ atoms}\cdot\text{cm}^{-3}$ or less and oxygen may be added selectively by ion-implantation to the channel forming regions of the TFT which constitute the pixel, to such an amount to give a concentration in the range of from 5×10^{20} to $5 \times 10^{21} \text{ atoms}\cdot\text{cm}^{-3}$. Since no light was irradiated to the TFTs in the peripheral circuit, it was effective to impart thereto a higher carrier mobility while reducing the oxygen concentration in order to realize a high frequency operation.

After the amorphous silicon film was deposited at a

thickness of from 500 to 5,000 Å, e.g., at a thickness of 1,500 Å, the amorphous silicon film was then heat-treated at a moderate temperature in the range of from 450 to 700°C for a duration of from 12 to 70 hours in a non-oxidizing atmosphere. More specifically, the film was maintained at 600°C under a hydrogen atmosphere. Since on the surface of the substrate was provided an amorphous silicon oxide layer under the silicon film, the whole structure was uniformly annealed because there was no nucleus present during the heat treatment.

The process can be explained as follows. That is, during the film deposition step, the film construction maintains the amorphous structure and the hydrogen is present as a mixture. The silicon film then undergoes phase transition from the amorphous structure to a structure having a higher degree of ordering by the annealing, and partly develops a crystallized portion. Particularly, the region which attains a relatively high degree of ordering at the film deposition of silicon tend to crystallize at this stage. However, the silicon bonding which bonds the silicon atoms each other attracts a region to another. This effect can be observed by a laser Raman spectroscopy as a peak shifted to a lower frequency side as compared with the peak at 522 cm^{-1} for a single crystal silicon. The apparent grain size can be calculated by the half width as 50 to 500 Å, i.e., a size corresponding to that of a microcrystal, but in fact, the film has a semi-amorphous structure comprising a plurality of those highly crystalline regions yielding a cluster structure, and the clusters are anchored to each other by the bonding between the silicon atoms.

The semi-amorphous film yields, as a result, a state in which no grain boundary (referred to hereinafter as GB) exists. Since the carrier easily moves between the clusters via the anchoring, a carrier mobility far higher than that of a

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polycrystalline silicon having a distinct GB can be realized. More specifically, a hole mobility, μ_h , in the range of from 10 to 200 $\text{cm}^2/\text{V}\cdot\text{sec}$ and an electron mobility, μ_e , in the range of from 15 to 300 $\text{cm}^2/\text{V}\cdot\text{sec}$, are achieved.

On the other hand, if a high temperature annealing in the temperature range of from 900 to 1200°C were to be applied in the place of a moderate temperature annealing as described hereinabove, impurities undergo a solid phase growth from the nuclei and segregate in the film. This results in the high concentration of oxygen, carbon, nitrogen, and other impurities at the GB into a barrier. Thus, despite the high mobility within a single crystal, the carrier is interfered at its transfer from a crystal to another by the barrier at the GB. In practice, it is quite difficult to attain a mobility higher than or equal to 10 $\text{cm}^2/\text{V}\cdot\text{sec}$ with a polycrystalline silicon at the present. Thus, in the liquid crystal display device according to the present invention, a semi-amorphous or a semi-crystalline structured silicon semiconductor is utilized.

Referring to FIG. 3(A), a process for fabricating a region 22 for a P-TFT and a region 13 for an N-TFT is described. The silicon film was masked with a first photomask <1>, and subjected to photo-etching to obtain the region 22 (having a channel width of 20 μm) for the P-TFT on the right-hand side of the FIGURE and the region 13 for the N-TFT on the left-hand side of the FIGURE.

On the resulting structure was deposited a silicon oxide film as the gate insulator film to a thickness of from 500 to 2,000 Å, e.g., to a thickness of 1,000 Å. The conditions or the film deposition were the same as those employed in depositing the silicon oxide film to give a blocking layer. Alternatively, a small amount of fluorine may be added during the film deposition to fix sodium ions.

Further on the gate insulator film was deposited a silicon film doped with phosphorus at a concentration of from 1×10^{21} to 5×10^{21} atoms \cdot cm $^{-3}$, or a multilayered film composed of said silicon film doped with phosphorus, having provided thereon a layer of molybdenum (Mo), tungsten (W), MoSi $_2$, or WSi $_2$. The resulting film was patterned using a second photomask <2> to obtain a structure as shown in FIG. 3(B). Then, a gate electrode 55 for the P-TFT, and a gate electrode 56 for the NTFT were established, for example, by depositing first a 0.2 μ m thick phosphorus(P)-doped silicon and a 0.3 μ m thick molybdenum layer thereon, at a channel length of 10 μ m. Referring to FIG. 3(C), a photoresist 57 was provided using a photomask <3>, and to a source 59 and a drain 58 for the P-TFT were added boron by ion implantation at a dose of from 1×10^{15} to 5×10^{15} cm $^{-2}$. Then, as shown in FIG. 3(D), a photoresist 61 was provided using a photomask <4>, and to a source 64 and a drain 62 for the N-TFT was added phosphorus by ion implantation at a dose of from 1×10^{15} to 5×10^{15} cm $^{-2}$. The processes above were carried out via a gate insulator film 54. However, referring to FIG. 3(B), the silicon oxide on the silicon film may be removed utilizing the gate electrodes 55 and 56 as the masks, and then boron and phosphorus may be directly added to the silicon film by ion implantation.

The structure thus obtained was re-annealed by heating at 600°C for a duration of from 10 to 50 hours. The impurities in the source 59 and drain 58 of the P-TFT and those in the source 64 and drain 62 of the N-TFT were activated to obtain P $^+$ and N $^+$ TFTs. Under the gate electrodes 55 and 56 were provided channel forming regions 60 and 63 with a semi-amorphous semiconductor.

According to the process for fabricating a liquid crystal display device of the present invention as described hereinabove, a CTFT can be obtained in a self-aligned method without elevating

the temperature to 700°C or higher. Thus, there is no need to use a substrate made of an expensive material such as quartz, and therefore it can be seen that the process is suited for fabricating liquid crystal display devices of large pixels according to the present invention.

The thermal annealing in this example was conducted twice, i.e., in the steps of fabricating the structures shown in FIGS. 3(A) and 3(D). However, the annealing at the step illustrated in FIG. 3(A) may be omitted depending to the desired device characteristics, and the annealing at the step shown in FIG. 3(D) can cover the total annealing. In this way it is possible to speed up the fabrication process.

Referring to FIG. 3(E), a silicon oxide film was deposited as an interlayer insulator 65 by the sputtering process mentioned hereinbefore. The method of depositing the silicon oxide film is not restricted to a sputtering method, and there may be employed LPCVD, photo CVD, or normal pressure CVD. The silicon oxide film was deposited, e.g., to a thickness of from 0.2 to 0.6 μm , and on it was perforated an opening 66 for the electrode using a photomask <5>. The structure was then wholly covered with aluminum by sputtering, and after providing lead portions 71 and 72, as well as contacts 67 and 68 using a photomask <6>, the surface thereof was coated with a smoothening film of an organic resin 69 such as a transparent polyimide resin, and subjected again to perforation for the electrodes using a photomask <7>.

As shown in FIG. 3(F), two insulated gate field effect thin film transistors were established in a complementary structure. To the output terminal thereof was provided an Indium Tin Oxide (ITO) film by sputtering to thereby connect the TFTs with one of the transparent pixel electrodes of the liquid crystal display device. In this case, the ITO film was deposited in the temperature range from room temperature to 150°C, and then

finished by annealing in oxygen or in atmosphere in the temperature range of from 200 to 400°C. The ITO film was then etched using a photomask <8> to form an electrode 70. Thus was finally obtained a structure comprising a P-TFT 22, an N-TFT 13, and an electrode 70 made of a transparent electrically conductive film on a single glass substrate 50. The resulting TFT yielded a mobility of $20 \text{ cm}^2/\text{V}\cdot\text{sec}$ and a V_{th} of -5.9 V for the P-TFT, and a mobility of $40 \text{ cm}^2/\text{V}\cdot\text{sec}$ and a V_{th} of 5.0 V for the N-TFT.

Referring to FIG. 6, the arrangement of electrodes and the like in the pixel portion of the liquid crystal display device is explained. An N-TFT 13 is assembled at the crossing of a first scanning line 15 and a data line 21, and another pixel N-TFT is provided at the crossing of the first scanning line 15 with another data line 14. On the other hand, a P-TFT is assembled at the crossing of a second scanning line 18 and a data line 21. Further, to the neighboring crossing of another first scanning line 16 and the data line 21 is provided another pixel N-TFT. Thus is accomplished a matrix structure using CTFTs. The N-TFT 13 is connected to the first scanning line 15 via a contact at the input terminal of the drain portion 64, and the gate portion 56 is connected to the data line 21 established in a multilayered wiring structure. The output terminal of the source portion 62 is connected to the pixel electrode 17 via a contact.

The P-TFT 22, on the other hand, is connected to the second scanning line 18 by the input terminal of the drain portion 58 via a contact, while the gate portion 55 is connected to the data line 21, and the output terminal of the source portion 59 is connected to the pixel electrode 17 via a contact in the same manner as in the N-TFT. In this manner is a single pixel established between (inner side) a pair of scanning lines 15 and 18, with a pixel 23 comprising a transparent electrode and a CTFT pair. By extending this basic pixel structure in four directions,

a 2 x 2 matrix can be scaled up to give a large pixel liquid crystal display device comprising a 640 x 480 or a 1280 x 960 matrix.

In FIGS. 4 and 5 are given the circuit diagrams for the peripheral circuit of the X direction. FIG. 4 illustrates the block function of the peripheral circuit being connected to a single wiring, and FIG. 5 shows the circuit diagram for connecting the transistor in the unit. FIG. 5 (A) corresponds to the block 7 in FIG. 4, and FIG. 5 (B) shows the circuit structure of the TFT corresponding to the block 8 in FIG. 4. It can be seen therefrom that the peripheral circuit is provided as a CMOS (complementary MOS) structure comprising an N-TFT 13 and a P-TFT 22 both fabricated in the same process as that employed for the switching device.

The substrate thus accomplished for use in the liquid crystal display device was laminated with the facing substrate by a known process, and an STN (super-twisted nematic) liquid crystal was injected between the substrates. The ICs 4 were used for the other part of the peripheral circuit. The ICs 4 were connected with each of the wirings for the Y direction on the substrate by a TAB process. Thus was completed a liquid crystal display device according to the present invention.

In the embodiment explained in the Example, only the peripheral circuit for the X direction was fabricated as TFTs following the same process used for the switching device, while leaving over the rest of the peripheral circuit as ICs having connected to the wirings of the Y direction. The present invention, however, is not only limited to this construction, and the portion which can be more easily fabricated into TFTs can be selected depending on the yield and the problems related to the process technology at the fabrication of the TFTs.

As described above, on the substrate a semiconductor film

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which comprises a semiconductor (amorphous silicon semiconductor in this Example) was formed extending over a display area and a peripheral circuit portion and subsequently the semiconductor (amorphous silicon semiconductor in this Example) is annealed into semi-amorphous or semi-crystal semiconductor. The semi-amorphous semiconductor yields a mobility ten times as high as, or even higher than that of the TFT using a conventional non-single crystal semiconductor. Thus, the TFT according to the present invention is well applicable to the peripheral circuits in which a rapid response is required, without subjecting the TFTs in the peripheral circuit portion to a special crystallization treatment which was requisite in the conventional TFTs; as a result, the TFTs for the peripheral circuit portion could be fabricated by the same process utilized for fabricating an active device of the display area, as described above.

EXAMPLE 2

In FIG. 7 is given a schematic view of a liquid crystal display device according to another embodiment of the present invention. The basic circuits and the like are the same as those employed in the liquid crystal display device described in Example 1. Referring to FIG. 7, the peripheral circuit connected to the wirings for the Y direction is constructed with ICs 4, and the ICs 4 are directly provided on the substrate by a COG method.

The pad electrodes of the ICs 4 can be connected with the wirings of the Y direction at a narrower interval by the use of a COG method instead of the TAB method. Thus, the process of the present example enables a finer display pixel design. Furthermore, since the ICs are provided on the substrate, the total volume of the display device remains almost unchanged to give a thinner liquid crystal display device.

EXAMPLE 3

Referring to FIG. 8, a liquid crystal display device having an $m \times n$ circuit structure is described below. Among the peripheral circuit portions (a means for supplying a signal to wirings of the X direction) connected to the wirings of the X direction, only an analog switch array circuit portion 1 is fabricated as TFTs in the same process as that used for fabricating the active device provided to a pixel 6. Furthermore, only an analog switch array circuit portion 2 in the peripheral circuit portion (a means for supplying a signal to wirings of the Y direction) connected to the wirings of the Y direction is also fabricated as TFTs, while providing the rest of the peripheral circuit portion by making them into ICs 4 having connected to a substrate using a COG method. The peripheral circuit portion provided as TFTs is in a CTFT structure (complementary structure) similar to the active device established to the pixels.

In FIG. 6 is provided the actual arrangement of the electrodes and the like corresponding to the circuit structure described above. However, the portion shown in FIG. 6 corresponds to a 2×2 matrix for the sake of simplicity.

Electrodes, TFTs, wirings, and the like were formed on a single substrate in the same fabrication process as that used in Example 1. In this process, the switching device (e.g. TFTs 13 and 22 in Fig.6) and a part of the peripheral circuits were fabricated in TFTs on the same substrate. This substrate was laminated with the facing substrate and an STN liquid crystal was injected between the substrates in the same manner as in Example 1.

The remaining peripheral circuit was established as ICs 4. The ICs 4 were connected with each of the wirings of the X and Y

Even when malfunctioning occurred on one of the TFTs, it was possible to maintain the display without suffering a perceptible defect.

EXAMPLE 4

Referring to a schematic diagram in FIG. 9, a liquid crystal display device according to another embodiment of the present invention is described below. The basic circuits and the like are the same as those of the liquid crystal display device described in Example 3. Among the peripheral circuits connected to the wirings of the Y direction in FIG. 9, the peripheral circuit portion composed of ICs 4 comprises ICs having directly established on the substrate by a COG method. The ICs 4 are divided into two portions, and one of them is provided at the upper portion of the substrate and the other is provided at the lower portion of the substrate. By employing such an arrangement, the pad electrodes of the ICs 4 and the wirings of the Y direction can be connected at a narrower interval as compared with the case in which the ICs are provided only on one side of the substrate. This structure can be therefore characterized by a finer display pixel design. Furthermore, since the ICs are directly bonded on the substrate, the structure can be realized with a negligible change in volume and hence enables a thinner liquid crystal display device.

In the examples described above, the TFTs of the active device were each fabricated into a CMOS structure. However, this structure is not requisite and modifications such as constructing the structure with only N-TFTs or with only P-TFTs are also acceptable. In these cases, however, the number of the devices in the peripheral circuit would be increased.

Furthermore, the position at which the TFTs are established can be varied. That is, the TFT need not be provided only to one side, i.e., only to either of the sides connected to the wirings of the X direction and the Y direction, but there may be also provided a second TFT on the other side to connect the TFTs in turns to halve the TFT density. Such a structure realizes an increase in the production yield.

The present invention provides a fine and precise liquid crystal display by overcoming the problems ascribed to the limitations related to the technological difficulty in the peripheral connections. Furthermore, the reliability on the connections is improved, since unnecessary connections between the outer peripheral circuits and the wirings along the X and Y directions are minimized.

The area occupation of the display substrate itself is reduced, since only a part of the peripheral circuits are fabricated into a TFT. It also allows a more freely designed substrate having a shape and dimension according to the requirements. Further it is possible to reduce the production cost, since the problems related to the production of the TFTs can be avoided while making those portions having a higher production yield into TFTs.

The use of a semi-amorphous semiconductor as the semiconductor film of the TFTs enables a rapid response, making the TFTs well applicable to peripheral circuits. Thus, the TFTs for the peripheral circuits are readily fabricated simultaneously utilizing the fabrication process for the active devices without any additional special treatments.

The liquid crystal display device according to the present invention provides a stable display because it operates without floating the liquid crystal potential. Furthermore, since the drive capacity of the CTFTs which function as the active devices

is high, the operational margin is increased. Since the peripheral driving circuit can be further simplified, it results in a more compact display device which is produced at a lower production cost. A high driving capacity can be realized with three signal lines and counter electrodes using a very simple signal. It is also possible to increase the switching rate. Even when a part of the TFTs should get out of order, a compensation function works to a certain degree. Since the carrier mobility increases to 10 times or more than that of a TFT using an amorphous silicon, the size of the TFT can be minimized and two TFTs can be connected to a single pixel without decreasing the aperture ratio. Furthermore, the advantages enumerated above can be realized by only using twice more the photomasks as compared with a conventional process in which only N-TFTs are used.

While the invention has been described in detail and with reference to specific embodiments thereof, it will be apparent to one skilled in the art that various changes and modifications can be made therein without departing from the spirit and scope thereof.

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WHAT IS CLAIMED IS:

1. An electro-optical device comprising:
 - a pair of substrates;
 - an electro-optical modulating layer provided between said substrates,
 - a plurality of thin film transistors provided on one of said substrates;
 - an electrode arrangement provided on said one of said substrates, said electrode arrangement being in the form of matrix and comprising a plurality of column lines connected to gate terminals of said thin film transistors and a plurality of row lines connected to source or drain terminals of said thin film transistors;
 - a first means for supplying an electric signal to said column lines, said first means being connected to said column lines; and
 - a second means for supplying an electric signal to said row lines, said second means being connected to said row lines,wherein one or both of said first and second means includes other thin film transistors provided on said one of said substrates.
2. The electro-optical device of claim 1 wherein only one of said first and second means includes other thin film transistors provided on said one of said substrates and the other one of said first and second means comprises a semiconductor chip.
3. The electro-optical device of claim 1 wherein said other thin film transistors are produced by the same process as said plurality of thin film transistors.
4. The electro-optical device of claim 3 wherein the

transistors have semi-amorphous semiconductor films.

5. The electro-optical device of claim 3 wherein the transistors are insulated gate field effect transistors.

6. The electro-optical device of claim 1 wherein one of source and drain terminals, which is not connected with said row lines, of each of said plurality of thin film transistors is provided with a pixel electrode.

7. The electro-optical device of claim 1 wherein said electro-optical modulating layer comprises a liquid crystal.

8. An electro-optical device comprising:

a pair of substrates;

an electro-optical modulating layer provided between said substrates,

a plurality of complementary thin film transistors provided on one of said substrates;

an electrode arrangement provided on said one of said substrates, said electrode arrangement being in the form of matrix and comprising a plurality of column lines connected to gate terminals of said transistors and a plurality of row lines connected to source or drain terminals of said transistors;

a first means for supplying an electric signal to said column lines, said first means being connected to said column lines; and

a second means for supplying an electric signal to said row lines, said second means being connected to said row lines,

wherein at least a part of said first and second means comprises other complementary thin film transistors provided on said one of said substrates.

9. The electro-optical device of claim 8 wherein other part of said first and second means comprises a semiconductor chip.

10. The electro-optical device of claim 8 wherein the transistors have semi-amorphous semiconductor films.

11. The electro-optical device of claim 8 wherein said other complementary thin film transistors are produced by the same process as said plurality of complementary thin film transistors.

12. The electro-optical device of claim 8 wherein the transistors are insulated gate field effect transistors.

13. The electro-optical device of claim 8 wherein one of source and drain terminals, which is not connected with said row lines, of each of said plurality of complementary thin film transistors is provided with a pixel electrode.

14. The electro-optical device of claim 8 wherein said electro-optical modulating layer comprises a liquid crystal.

15. A method for manufacturing an electro-optical device comprising a pair of substrates, an electro-optical modulating layer provided between said substrates, a plurality of pixels comprising a plurality of insulated gate field effect transistors for driving said pixels, said transistors being provided on one of said substrates, and means for supplying an electric signal to said insulated gate field effect transistor, said method comprising:

forming channels of said plurality of insulated gate field effect transistors and a channel of an insulated gate field

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effect transistor constituting a part of said means at the same time by forming on said one of said substrates a semiconductor film which comprises a semiconductor and extends over regions to become said channels of said plurality of insulated gate field effect transistors and a region to become said channel of an insulated gate field effect transistor constituting a part of said means and subsequently annealing said semiconductor into semi-amorphous or semi-crystal semiconductor.

16. The method of claim 15 wherein other part of said means comprises a semiconductor chip.

17. The method of claim 15 wherein said annealing is carried out in a non-oxide atmosphere.

18. The method of claim 15 wherein said semiconductor before said annealing comprises an amorphous semiconductor.

19. The method of claim 18 wherein said annealing is carried out at a temperature of 450°C to 700°C.

20. The method of claim 15 wherein said electro-optical modulating layer comprises a liquid crystal.

ABSTRACT

An electro-optical device and a method for manufacturing the same are disclosed. The device comprises a pair of substrates and an electro-optical modulating layer (e.g. a liquid crystal layer having sandwiched therebetween, said pair of substrates consisting of a first substrate having provided thereon a plurality of gate wires, a plurality of source (drain) wires, and a pixel matrix comprising thin film transistors, and a second substrate facing the first substrate, wherein, among the peripheral circuits having established on the first substrate and being connected to the matrix wirings for the X direction and the Y direction, only a part of said peripheral circuits is constructed from thin film semiconductor devices fabricated by the same process utilized for an active device, and the rest of the peripheral circuits is constructed from semiconductor chips. The liquid crystal display device according to the present invention is characterized by that the peripheral circuits are not wholly fabricated into thin film transistors, but only those portions having a simple device structure, or those composed of a small number of devices, or those comprising an IC not easily available commercially, or those comprising an expensive integrated circuit, are fabricated by thin film transistors. According to the present invention, an electro-optical device is provided at an increased production yield with a reduced production cost.

Fig. 1

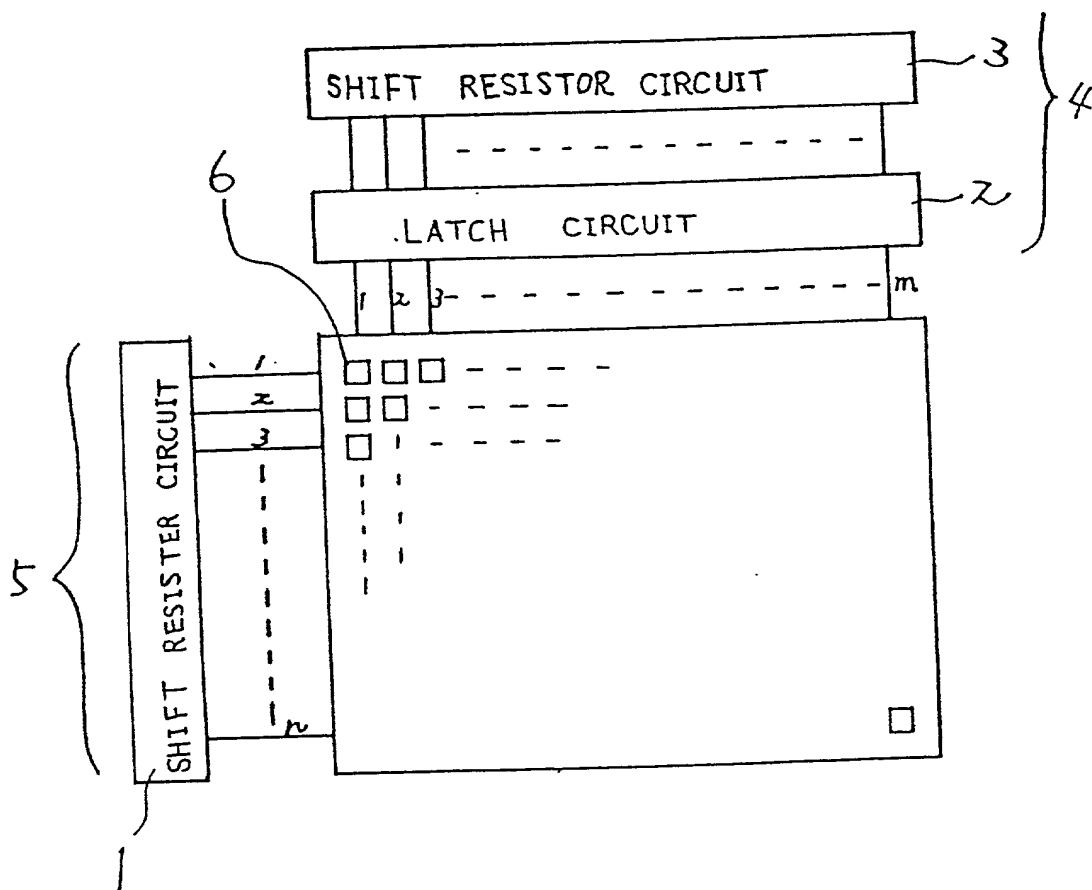


Fig. 2

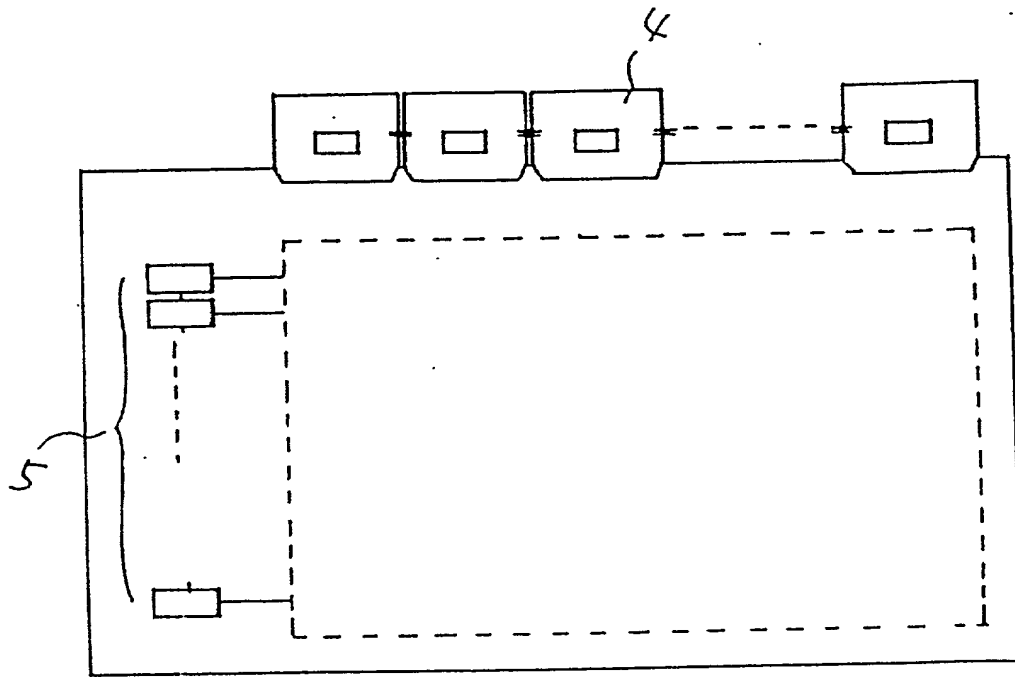
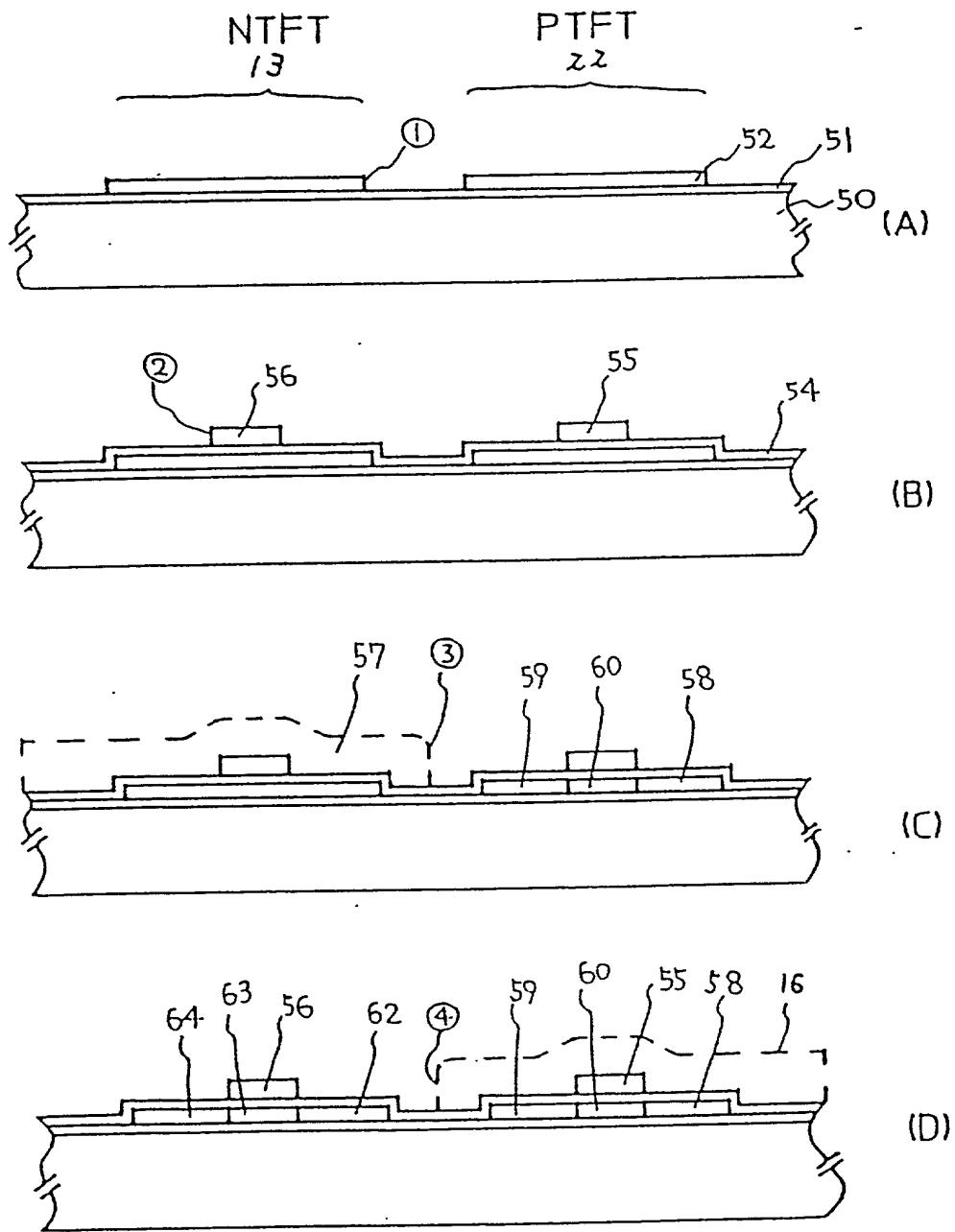


Fig. 3



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Fig. 4

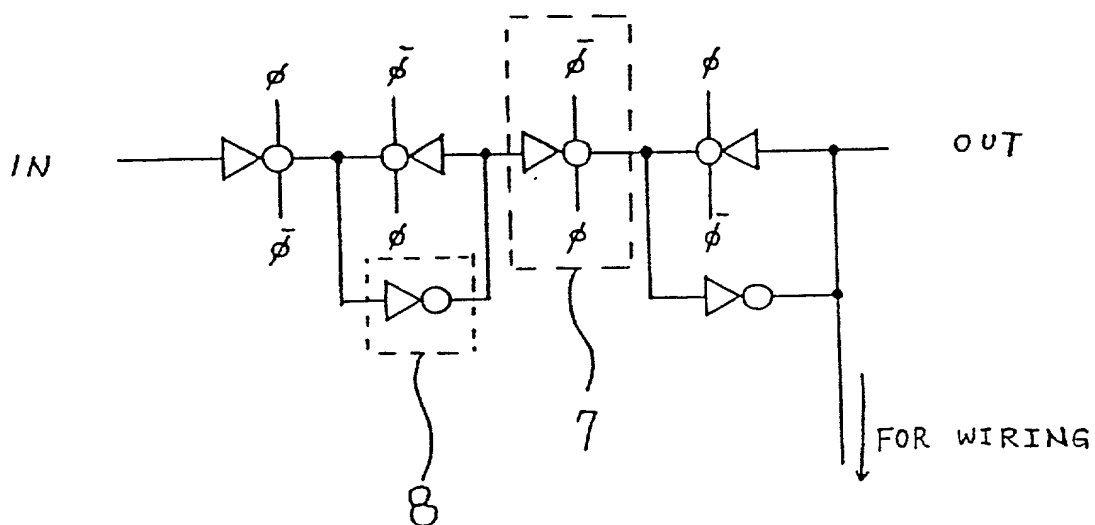


Fig. 5

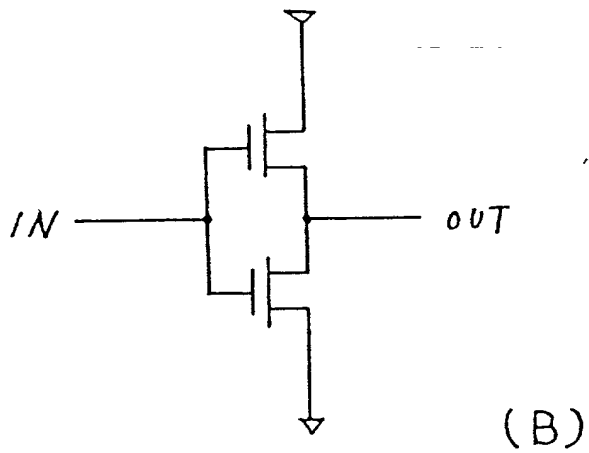
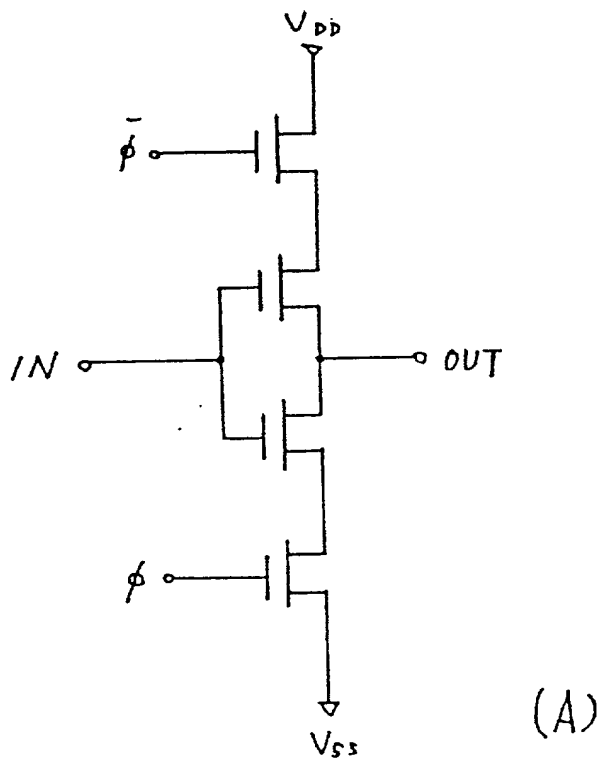


Fig. 6

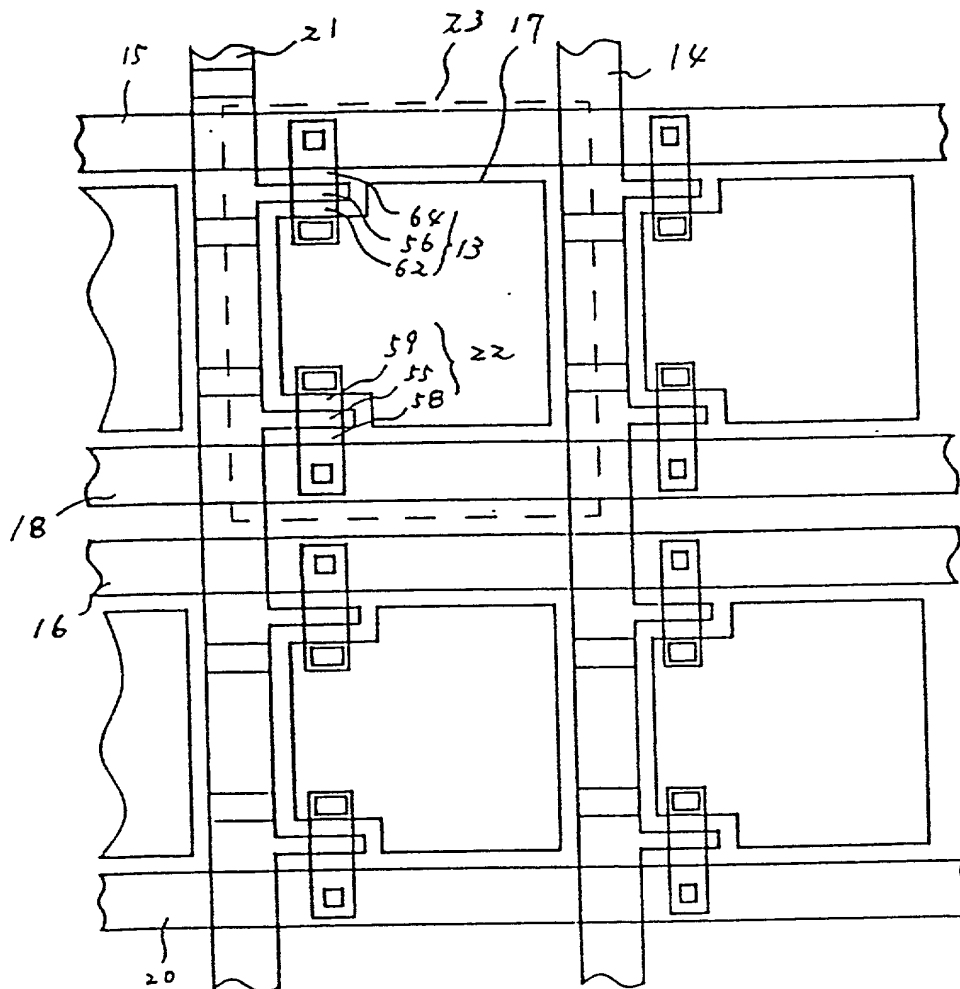
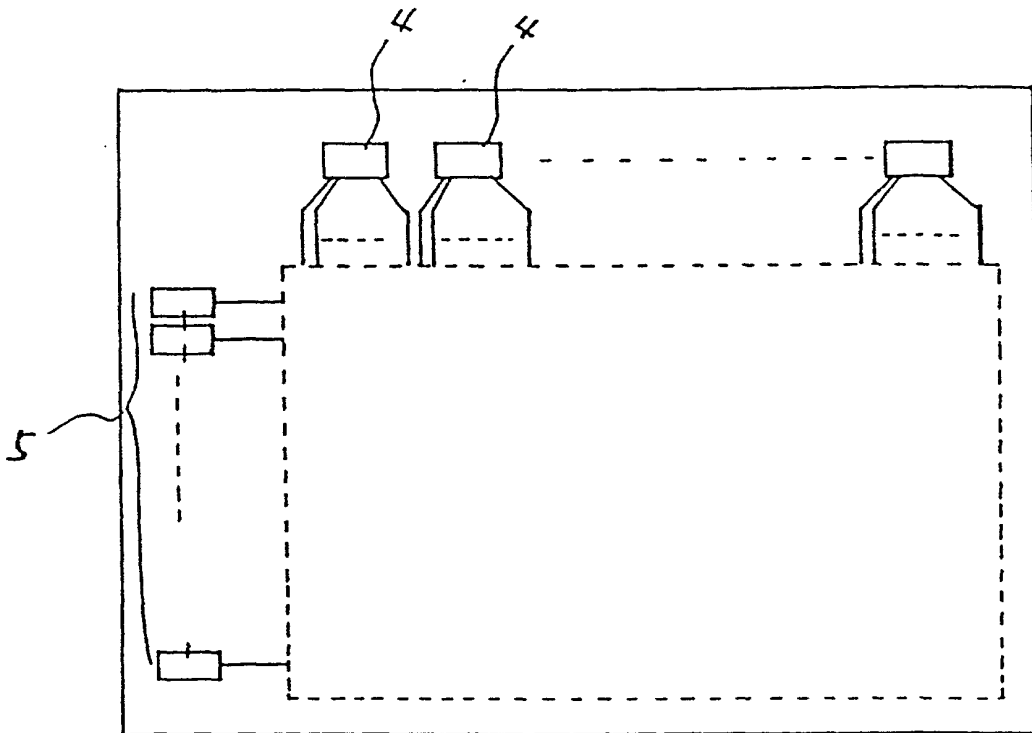


Fig. 7



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Fig. 8

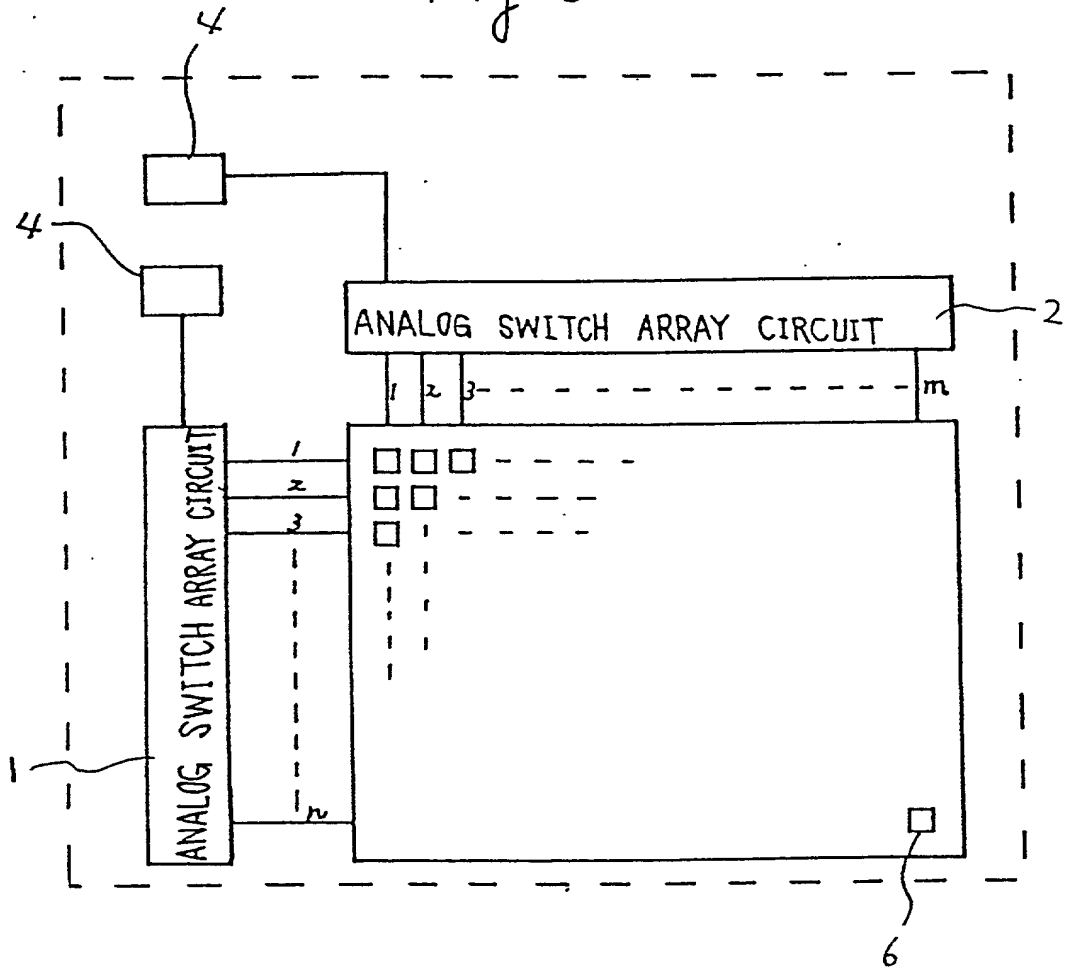
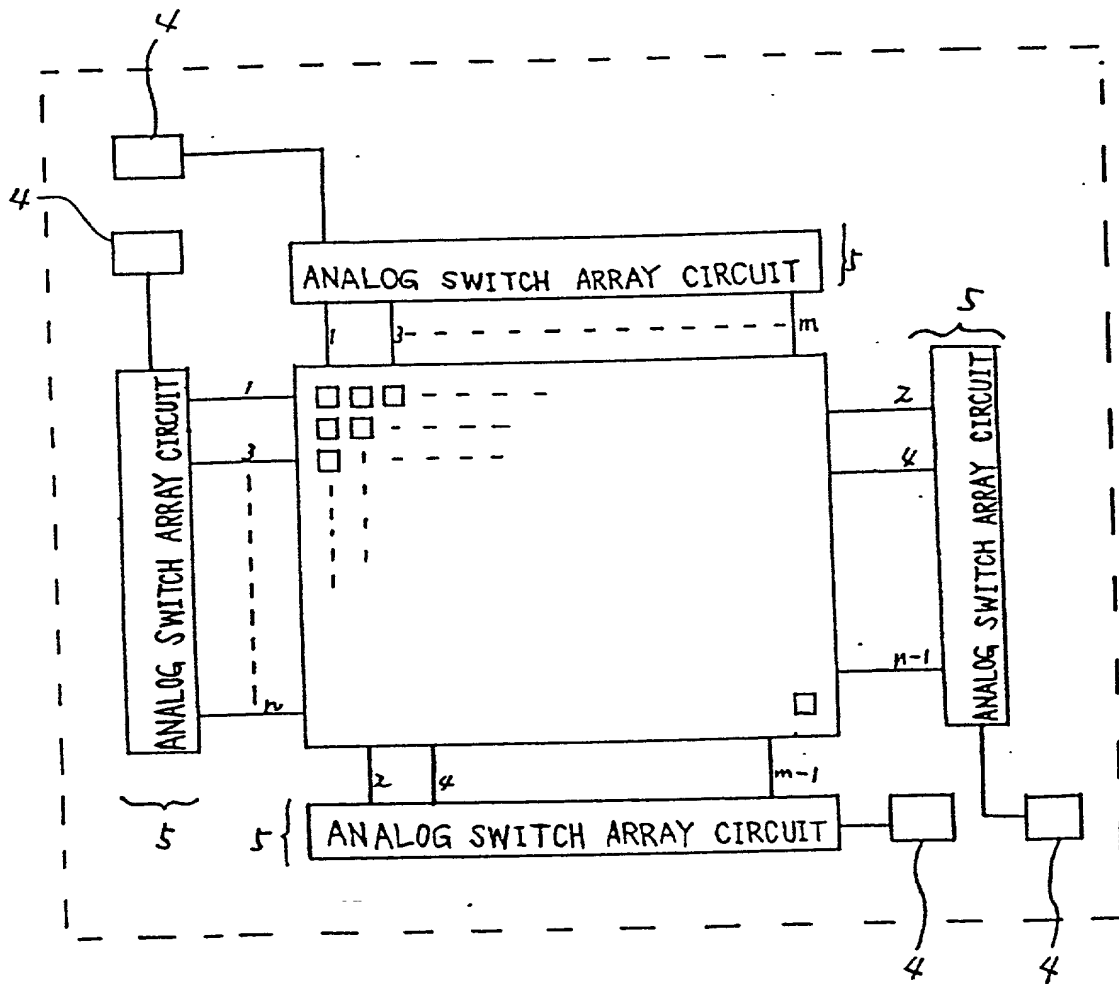


Fig. 9



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As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named below) of the invention entitled: * ELECTRO-OPTICAL DEVICE AND METHOD FOR MANUFACTURING

THE SAME

_____, the specification of which is attached hereto unless the following box is checked:

Check Box If
Appropriate —
For Use Without
Specification
Attached

☐ The specification was filed on _____
and was assigned Serial No. _____
and was amended on _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

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Priority Claimed

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Information
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2-418367 (Number)	JAPAN (Country)	12/25/1990 (Month/Day/Year Filed)	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
2-418366 (Number)	JAPAN (Country)	12/25/1990 (Month/Day/Year Filed)	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Month/Day/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Month/Day/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
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(Application Serial No.)	(Filing Date)	(Status—patented, pending, abandoned)
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(Application Serial No.)	(Filing Date)	(Status—patented, pending, abandoned)
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I hereby appoint the following attorneys to prosecute this application and/or an international application and to transact all business in the Patent and Trademark Office connected therewith:

Daniel W. Sixbey (Reg. No. 20,932)
 Stuart J. Friedman (Reg. No. 24,312)
 Charles M. Leedom, Jr. (Reg. No. 26,477)

Gerald J. Ferguson, Jr. (Reg. No. 23,016)
 David S. Safran (Reg. No. 27,997)
 Thomas W. Cole (Reg. No. 28,290)

Send Correspondence to:

SIXBEY, FRIEDMAN, LEEDOM & FERGUSON, P.C.
 2010 Corporate Ridge, Suite 600
 McLean, Virginia 22102
 Telephone: (703) 790-9110

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Insert Full Name of First or Sole Inventor and Date This Document Is Signed

Insert Residence
 Insert Citizenship

Insert Post Office Address

Second Inventor:
 see above

Third Inventor:
 see above

Fourth Inventor:
 see above

FULL NAME OF SOLE OR FIRST INVENTOR	INVENTOR'S SIGNATURE	DATE
Shunpei YAMAZAKI	<i>Shunpei Yamazaki</i>	12/16/1991
RESIDENCE (City, State & Country)	CITIZENSHIP	
Tokyo Japan	Japanese	
POST OFFICE ADDRESS (Complete Street Address including City, State & Country)		
21-21, Kirakarasuyama, 7-chome, Setagaya-ku, Tokyo 157 Japan		
FULL NAME OF SECOND JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City, State & Country)	CITIZENSHIP	
POST OFFICE ADDRESS (Complete Street Address including City, State & Country)		
FULL NAME OF THIRD JOINT INVENTOR, IF ANY	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City, State & Country)	CITIZENSHIP	
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